



Contains Confidential and Proprietary Information on GDI Adhesive Products
TDS Should Not Be Shared With 3rd Parties Without GDI Adhesives Consent

Typical Properties

DESCRIPTION

P-2000 is a safe, non-hazardous, highly effective hot melt-cleaning compound. It has a pleasant odor and is environmentally friendly. Use of P-2000 helps reduce downtime and increases productivity. Prevents binding of applicator wheels, erratic pump stroking and loosens charred material. Also, prevents nozzle clogging and hose constrictions.

P-2000 hot melt purge is designed for flushing reactive PUR hot melt adhesives from hot melt application equipment to prevent the cured hot melt from seizing up the nozzles and curing inside the applicator.

Also, used for cleaning general hot melt equipment that contains EVA, polyethylene, rubber based PSAs and Polyamides to remove oxidized and charred material.

PHYSICAL PROPERTIES

Appearance	Green
Melting Point	176°F
Application Temperature	250-325°F
Viscosity	Approx. 6,000 cps @ 300°F Approx. 3,000 cps @ 325°F
Storage Stability	Store in a cool, dry place
Shelf Life	5 years

SUGGESTED USES

P-2000 dissolves thermoplastic hot melt adhesives by dropping the adhesive viscosity and loosening charred material, which can then be flushed from the system, eliminating the waste of purging large quantities of adhesives through equipment.

Use of P-2000 as part of a regular preventative maintenance program eliminates costly unscheduled line shutdowns.

Upon start-up after the purging process, remove any excess P-2000 purge out of the nozzle prior to assembly using the reactive PUR hot melts.

P-2000 can be used on food packaging glue lines.

PURGE FORM:

- 10 oz cartridges (i.e. PAM 500K, REKA TR 80.3, TR 50.3, 3M, etc).
- 5-gallon metal pails and 55 gallon drums for bulk equipment.
- 50 lbs boxes in pellet form.

ADVANTAGES OF P-2000 vs. WAX

- P-2000 has more body to it and will push and flush hot melt out of the hose and nozzles, where wax is too thin when melted to do any cleansing. Wax will simply run next to the hot melt without push or carrying it out of the equipment.
- Wax, being very low viscosity, tends to be a splash hazard.
- P-2000 will penetrate the char and loosen, where wax cannot do this.



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INSTRUCTIONS

Use P-2000 at the processing temperature of the adhesive in the system.

1. Drain the system of all hot melt adhesive. Mechanically clean the feed area as needed, then remove nozzles and screens to prevent blockage from loosened degraded material.
2. For systems with nozzle clogging problems or char build up; fill the melt pot with P-2000 and melt to adhesive application temperature. Run the pump until the green purge exits the hose/feed line for the nozzles. Turn off the pump and maintain the purge cleaner at the adhesive application temperature or 325°F (whichever is the higher of the two) for one hour. After the one-hour period (longer cook times are OK), drain or pump the purge out of the melt pot. Turn the pump off. Install clean filters and the nozzles, and then add enough purge to the melt pot for the purging of the hose and nozzles. After the purge has reached application temperature, pump the remaining purge through the system.
3. For systems that need to change adhesives: fill the melt pot with P-2000 and melt to adhesive application temperature. Maintain the purge cleaner at the adhesive application temperature or 325°F (whichever is the lower of the two) for 15 minutes. Pump the purge through the system for five minutes. Drain or pump the remaining purge out of the melt pot.
4. For hot melt application guns: use a 10 oz. Cartridge to purge nozzles for cartridge style guns. Use P-2000 pellets to purge and clean bulk loaded guns. Fill the bulk-loading gun with P-2000 and heat to 325°F. When melted, extrude purge until the extruded material is green. Then completely fill the unit with purge and permit it to heat to 325°F. To purge, extrude the purge after 15 minutes at temperature or for cleaning char, heat for one hour and then remove the P-2000. After the use of the P-2000, flush the gun with the next hot melt to be used.
5. Add enough new hot melt adhesive to the melt pot to flush the purge from the system. This usually is about 1/3 of the melt pot.
6. After the adhesive is at application temperature, pump it through the system.
7. The system is now ready for use.

The data contained herein are furnished for informational purposes only as typical values and are believed to be correct as of the date of issue. It is the user's responsibility to determine whether the Glue Dots product is fit for a particular purpose and suitable for user's method of use or application. Glue Dots International makes no warranties, expressed or implied, including, but not limited to, any implied warranty of merchantability or fitness for a particular purpose as a result of sale of products.

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Regulatory Details

FDA Status:

The components of this product comply with the compositional requirements of the:

FDA Indirect Food Additive Regulation, 21 CFR 175.105, Adhesive.

REACH Status:

The supplier(s) to GDI Adhesives have documented that Substances of Very High Concern (SVHC) are not intentionally added or used in the manufactured of products and the raw materials supplied do not intentionally contain any substances found on the candidate list, nor does the product(s) contain any SVHCs above the threshold limits of 0.1% (w/w).

ROHS Status:

The substances of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), polybrominated diphenyl ethers (PBDE) including Decabrominated diphenyl ether (DecaBDE), Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), or Diisobutyl phthalate (DIBP) are not intentionally added or used in the manufacture of the product, or do not exceed specified limits.

Chemical Inventory:

All ingredients in these products are in compliance with the following chemical inventories:

- United States: Toxics Substances Control Act Inventory (TSCA)
- Canada: Domestic Substances List (DSL) or Non-Domestic Substances List (NDSL)
- Europe: EINECS/ELINCS replaced by REACH
- Australia: Australian Inventory of Chemical Substances (AICS)
- New Zealand: New Zealand Inventory of Chemicals (NZIoC)
- Korea: Korean Existing Chemicals List (KECL)
- Japan: Japanese Inventory of Existing and New Chemical Substances (ENCS)
- The Philippines: Philippines Inventory of Chemicals and Chemical Substances (PICCS)
- China: Inventory of Existing Chemical Substances Manufactured or Imported in China (IECSC)
- Taiwan: Existing Chemical Substances Inventory (ECSI)

VOC Status:

The non-solid portion of this waterbased adhesive is comprised solely of de-ionized water. Volatile organic compounds nor Hazardous Air Pollutants are used in either the manufacture of the raw materials, nor in the manufacturing setting of GDI Adhesives for this product.

CONEG, Coalition of Northeastern Governors:

There are no heavy metals (Cadmium, Lead, Chromium (Hexavalent) & Mercury) or its compounds incorporated into the production and formulation of these products, and reasonably results in compliance to CONEG which regulates total incidental cadmium, lead, chromium (VI) and mercury less than 100 ppm.

Proposition 65, California's Safe Drinking Water and Toxic Enforcement Act of 1986

The product does not contain any Proposition 65 chemicals, or for the substances that are present, the levels are estimated to be less than 1 mg/kg and less than 0.1 mg/kg as specified.

Conflict Minerals Compliance:

The suppliers of raw materials to GDI Adhesives have documented that they do not intentionally add any Conflict Minerals (metals or compounds of gold (Au), tantalum (Ta), Tungsten (W), cobalt (Co) and tin (Sn)) during the manufacture of their product, and GDI Adhesives does not intentionally add conflict materials during the production process of GDI Adhesives products.

These statements are based upon information provided by the supplier(s) of the raw materials used in the manufacture of this product. The information is determined to the best of our ability as derived using supplier information as well as their understanding of the applicable regulation(s). The evaluations are based upon known composition information and are not based on analytical testing. Our suppliers and GDI Adhesives do not routinely analyze our products for substances not intentionally added.

These statements are updated as needed with new revisions depending on changes in disclosure of our supplier(s), and/or amendments to the stated regulations GDI Adhesive is disclosing compliance with.